Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	32717	semiconductor and ((bonding or electrode) adj pad)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/21 15:56
L2	8166	1 and interconnect$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/21 15:57
L3	331	2 and dummy and (around or surround$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/21 15:57